

Material Composition Data



Product: GXO-3201

Page 1

GXO-3201 - 1.8~3.3V SM Oscillator

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Base	Ag-Cu	Ag	7440-22-4	0.520	4.01
	Ag-Cu	Cu	7440-50-8	0.090	0.69
	Ceramic	Al ₂ O ₃	1344-28-1	7.716	59.52
	Ceramic	Cr ₂ O ₃ (Non hex)	1308-38-9	0.054	0.42
	Ceramic	Mo	7439-98-7	0.108	0.83
	Ceramic	SiO ₂	14808-60-7	0.380	2.93
	Gold plate	Au	7440-57-5	0.185	1.43
	Kovar ring	Co	7440-48-4	0.330	2.55
	Kovar ring	Fe	7439-89-6	0.860	6.63
	Kovar ring	Ni	7440-02-0	0.620	4.78
	Mo-W	Mo	7439-98-7	0.016	0.12
	Mo-W	W	7440-33-7	1.690	13.04
	Nickel	Ni	7440-02-0	0.395	3.05
	Blank	Quartz	SiO ₂	14808-60-7	0.509
Conductive adhesive	Silicone resin	Ag	7440-22-4	0.020	90.91
	Silicone resin	Si	7440-21-3	0.002	9.09
Electrode	Metal	Ag	7440-22-4	0.003	100.00
IC DIE	Gold wire	Au	7440-57-5	1.640	76.53
	Si-Al	Al	7429-90-5	0.004	0.19
	Si-Al	Si	7440-21-3	0.499	23.29
Lid	Kovar	Co	7440-48-4	0.330	15.87
	Kovar	Fe	7439-89-6	1.030	49.52
	Kovar	Ni	7440-02-0	0.560	26.92
	Nickel	Ni	7440-02-0	0.160	7.69
Total Mass:				17.721 mg	

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